

Title (en)

AUTOClave BONDING OF SPUTTERING TARGET ASSEMBLY

Title (de)

VERBINDUNG VON ZERSTÄUBUNGSTARGETS IM AUTOKLAVEN

Title (fr)

COLLAGE EN AUTOCLAVE D'UN ENSEMBLE CIBLE DE PULVERISATION CATHODIQUE

Publication

EP 0752017 A1 19970108 (EN)

Application

EP 95910130 A 19950125

Priority

US 9501089 W 19950125

Abstract (en)

[origin: WO9623085A1] Fabrication techniques for an integrated sputtering target assembly include pressure assisted bonding of soldered layers of material, in particular, soldering of the target material to its backing plate; pressure assisted curing of structural adhesives used to join a finned cover plate (52) to a backing plate (50) which between them form passages for fluid cooling; and bonding an electrical insulating layer to the back surface of the backing plate. The pressure to assist in bonding is typically applied by an autoclave. The cooling fluid passages disposed between a cover and a finned backing plate can be sealed by using laser welding or electron beam welding rather than closing the cooling passages with structural adhesives.

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IPC 8 full level

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